# FOR USE AS LAMP, RELAY, OR MOS DRIVERS

- Low-Voltage Version of SN54LS145/ SN74LS145
- Full Decoding of Input Logic
- SN74LS445 Has 80-mA Sink-Current Capability
- All Outputs Are Off for Invalid BCD Input Conditions
- Low Power Dissipation . . . 35 mW Typical

## logic

#### **FUNCTION TABLE**

NO.		NP	UTS					0	UTF	ידטי	S			
NO.	D	С	В	Α	0	1	2	3	4	5	6	7	8	9
0	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н
1	L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	Н	н
2	L	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н	Н	н
3	Ļ	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н	Н	н
4	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н	Н	Н
5	L	Н	L	Н	н	Н	Н	Н	Н	L	Н	Н	Н	н
6	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н	н
7	L	Н	Н	Н	н	Н	Н	Н	Н	Н	Н	L	Н	н
8	н	L	L	L	н	Н	Н	Н	Н	Н	Н	Н	L	н
9	Н	L	L	Н	н	Н	Н	Н	Н	Н	Н	Н	Н	L
	Н	L	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
	Н	L	н	Н	Н	Н	Н	Н	Н	Н	Н	Н	H	Н
1	Н	Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
INVALID	Н	Н	L	Н	н	Н	Н	Н	Н	Н	н	Н	Н	Н
=	н	Н	Н	L	н	Н	Н	Н	Н	Н	Н	Н	Н	Н
	н	Н	Н	Н	Н	н	Н	Н	Н	Н	Н	Н	Н	Н

H = high level (off), L = low level (on)

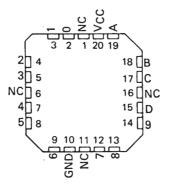
# description

These monolithic BCD-to-decimal decoder/drivers consist of eight inverters and ten four-input NAND gates. The inverters are connected in pairs to make BCD input data available for decoding by the NAND gates. Full decoding of valid BCD input logic ensures that all outputs remain off for all invalid binary input conditions. These decoders feature high-performance, n-p-n output transistors designed for use as indicator/ relay drivers or as open-collector logic-circuit drivers. Each of the output transistors will sink up to 80 milliamperes of current. Each input is one Series 54LS/ 74LS standard load. Inputs and outputs are entirely compatible for use with TTL logic circuits, and the outputs are compatible for interfacing with most MOS integrated circuits. Power dissipation is typically 35 milliwatts.

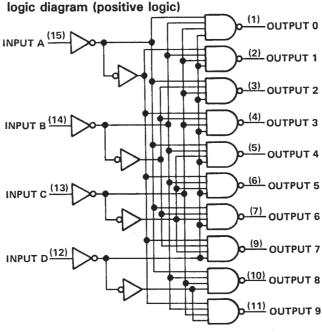
SN54LS445 . . . J PACKAGE SN74LS445 . . . D OR N PACKAGE (TOP VIEW)

0[	1	U <sub>16</sub>	□vcc
1[	2	15	] A
2[	3	14	В
3[	4	13	] C
4[	5	12	] D
5	6	11	] 9
6[	7	10	<u></u> 8
GND[	8	9	<b>_</b> 7

SN54LS445 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection



Pin numbers shown are for D, J, and N packages.



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		 7 V
Input voltage		 7 V
Operating free-air temperature range:	N54LS445	 -55°CC to 125°C
	N74LS445	 0°C to 70°C
Storage temperature range		 -65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

# recommended operating conditions

	SI	SN54LS445			SN74LS445		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
Off-state output voltage, VO(off)			7			7	V
Operating free-air temperature, TA	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS445			SN74LS445			
			TEST CONDITIONS.		TYP‡	MAX	MIN	TYP‡	MAX	UNIT
$V_{IH}$	High-level input voltage			2			2			V
VIL	Low-level input voltage					0.7			0.8	V
ViK	Input clamp voltage	VCC = MIN,	I <sub>I</sub> = -18 mA			-1.5			-1.5	V
IO(off)	Off-state output current	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max,	V <sub>iH</sub> = 2 V, V <sub>OH</sub> = 7 V			250			250	μА
	On-state output voltage	VCC = MIN,	I <sub>OL</sub> = 12 mA	0.25 0.4		0.4		0.25	0.4	
VO(on)		V <sub>IH</sub> = 2 V, ,	I <sub>OL</sub> = 24 mA					0.35	0.5	1 v
		VIL = VIL max	I <sub>OL</sub> = 80 mA					2.3	3	1
Ц	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 7 V			0.1			0.1	mA
ΉΗ	High-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V			20			20	μА
11L	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V			-0.4			-0.4	mA
ICC	Supply current	V <sub>CC</sub> = MAX,	See Note 2		. 7	13		7	13	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

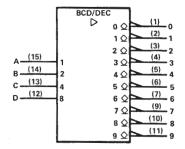
NOTE 2: ICC is measured with all inputs grounded and outputs open.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER		TEST CONDITI	ONS	MIN	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output	C <sub>1</sub> = 45 pF,	$R_1 = 665 \Omega$ .	See Note 3		50	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	CL - 45 pr,	uf - 902 75'	000 11010 3		50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

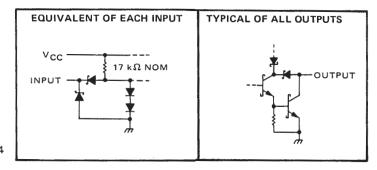
## logic symbol†



<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

# schematic of inputs and outputs





 $<sup>^{\</sup>ddagger}$ All typical values are at  $V_{CC}$  = 5 V,  $T_{A}$  = 25°C.





i.com 18-Sep-2008

## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LS445D	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
SN74LS445N	OBSOLETE	PDIP	N	16	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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